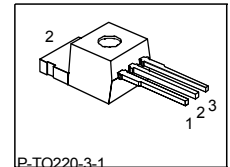


**Cool MOS™ Power Transistor**
**Feature**

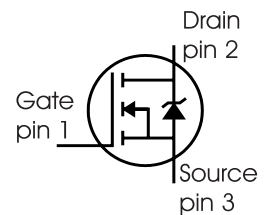
- New revolutionary high voltage technology
- Ultra low gate charge
- Periodic avalanche rated
- Extreme  $dv/dt$  rated
- Ultra low effective capacitances
- Improved transconductance
- Pb-free lead plating; RoHS compliant
- Qualified according to JEDEC<sup>0)</sup> for target applications

$V_{DS}$	600	V
$R_{DS(on)}$	1.4	$\Omega$
$I_D$	3.2	A

PG-TO220



Type	Package	Ordering Code	Marking
SPP03N60S5	PG-TO220	Q67040-S4184	03N60S5


**Maximum Ratings**

Parameter	Symbol	Value	Unit
Continuous drain current $T_C = 25\text{ }^\circ\text{C}$ $T_C = 100\text{ }^\circ\text{C}$	$I_D$	3.2 2	A
Pulsed drain current, $t_p$ limited by $T_{jmax}$	$I_{D\text{ puls}}$	5.7	
Avalanche energy, single pulse $I_D = 2.4\text{ A}$ , $V_{DD} = 50\text{ V}$	$E_{AS}$	100	mJ
Avalanche energy, repetitive $t_{AR}$ limited by $T_{jmax}$ <sup>1)</sup> $I_D = 3.2\text{ A}$ , $V_{DD} = 50\text{ V}$	$E_{AR}$	0.2	
Avalanche current, repetitive $t_{AR}$ limited by $T_{jmax}$	$I_{AR}$	3.2	A
Gate source voltage	$V_{GS}$	$\pm 20$	V
Gate source voltage AC ( $f > 1\text{ Hz}$ )	$V_{GS}$	$\pm 30$	
Power dissipation, $T_C = 25\text{ }^\circ\text{C}$	$P_{tot}$	38	W
Operating and storage temperature	$T_j, T_{stg}$	-55... +150	$^\circ\text{C}$

**Maximum Ratings**

Parameter	Symbol	Value	Unit
Drain Source voltage slope $V_{DS} = 480 \text{ V}$ , $I_D = 3.2 \text{ A}$ , $T_j = 125 \text{ }^\circ\text{C}$	$dv/dt$	20	V/ns

**Thermal Characteristics**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Thermal resistance, junction - case	$R_{thJC}$	-	-	3.3	K/W
Thermal resistance, junction - ambient, leaded	$R_{thJA}$	-	-	62	
SMD version, device on PCB: @ min. footprint @ 6 cm <sup>2</sup> cooling area <sup>2)</sup>	$R_{thJA}$	-	-	62	
Soldering temperature, wavesoldering 1.6 mm (0.063 in.) from case for 10s <sup>3)</sup>	$T_{sold}$	-	-	260	$^\circ\text{C}$

**Electrical Characteristics, at  $T_j=25^\circ\text{C}$  unless otherwise specified**

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{V}$ , $I_D=0.25\text{mA}$	600	-	-	V
Drain-Source avalanche breakdown voltage	$V_{(BR)DS}$	$V_{GS}=0\text{V}$ , $I_D=3.2\text{A}$	-	700	-	
Gate threshold voltage	$V_{GS(th)}$	$I_D=135\mu\text{A}$ , $V_{GS}=V_{DS}$	3.5	4.5	5.5	
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=600\text{V}$ , $V_{GS}=0\text{V}$ , $T_j=25^\circ\text{C}$ , $T_j=150^\circ\text{C}$	-	0.5	1	$\mu\text{A}$
			-	-	70	
Gate-source leakage current	$I_{GSS}$	$V_{GS}=20\text{V}$ , $V_{DS}=0\text{V}$	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10\text{V}$ , $I_D=2\text{A}$ , $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$	-	1.26	1.4	$\Omega$
			-	3.4	-	

**Electrical Characteristics** , at  $T_j = 25\text{ }^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
<b>Characteristics</b>						
Transconductance	$g_{fs}$	$V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}$ , $I_D = 2\text{A}$	-	1.8	-	S
Input capacitance	$C_{iss}$	$V_{GS} = 0\text{V}$ , $V_{DS} = 25\text{V}$ , $f = 1\text{MHz}$	-	420	-	pF
Output capacitance	$C_{oss}$		-	150	-	
Reverse transfer capacitance	$C_{rss}$		-	3.6	-	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 350\text{V}$ , $V_{GS} = 0/10\text{V}$ , $I_D = 3.2\text{A}$ , $R_G = 20\Omega$	-	35	-	ns
Rise time	$t_r$		-	25	-	
Turn-off delay time	$t_{d(off)}$		-	40	-	
Fall time	$t_f$		-	15	22.5	

**Gate Charge Characteristics**

Gate to source charge	$Q_{gs}$	$V_{DD} = 350\text{V}$ , $I_D = 3.2\text{A}$	-	3.5	-	nC
Gate to drain charge	$Q_{gd}$		-	7	-	
Gate charge total	$Q_g$	$V_{DD} = 350\text{V}$ , $I_D = 3.2\text{A}$ , $V_{GS} = 0\text{ to }10\text{V}$	-	12.4	16	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} = 350\text{V}$ , $I_D = 3.2\text{A}$	-	8	-	V

<sup>0</sup>J-STD20 and JESD22

<sup>1</sup>Repetitive avalanche causes additional power losses that can be calculated as  $P_{AV} = E_{AR} \cdot f$ .

<sup>2</sup>Device on 40mm\*40mm\*1.5mm epoxy PCB FR4 with 6cm<sup>2</sup> (one layer, 70 μm thick) copper area for drain connection. PCB is vertical without blown air.

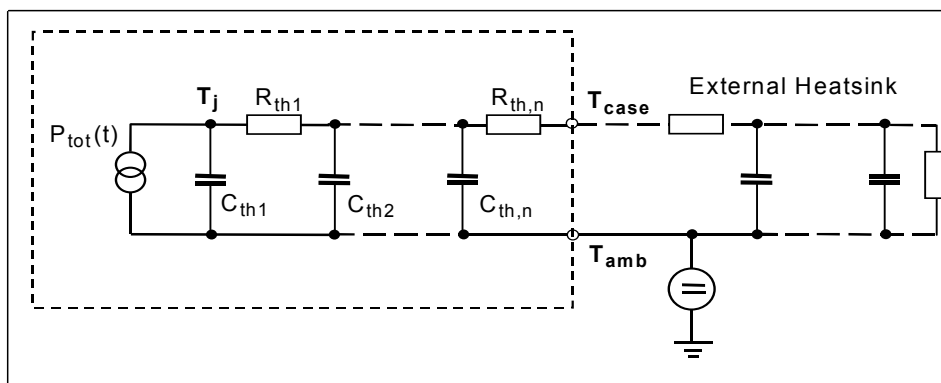
<sup>3</sup>Soldering temperature for TO-263: 220°C, reflow

**Electrical Characteristics**, at  $T_j = 25\text{ }^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Inverse diode continuous forward current	$I_S$	$T_C=25^\circ\text{C}$	-	-	3.2	A
Inverse diode direct current, pulsed	$I_{SM}$		-	-	5.7	
Inverse diode forward voltage	$V_{SD}$	$V_{GS}=0\text{V}, I_F=I_S$	-	1	1.2	V
Reverse recovery time	$t_{rr}$	$V_R=350\text{V}, I_F=I_S,$	-	1000	1700	ns
Reverse recovery charge	$Q_{rr}$	$di_F/dt=100\text{A}/\mu\text{s}$	-	2.3	-	$\mu\text{C}$

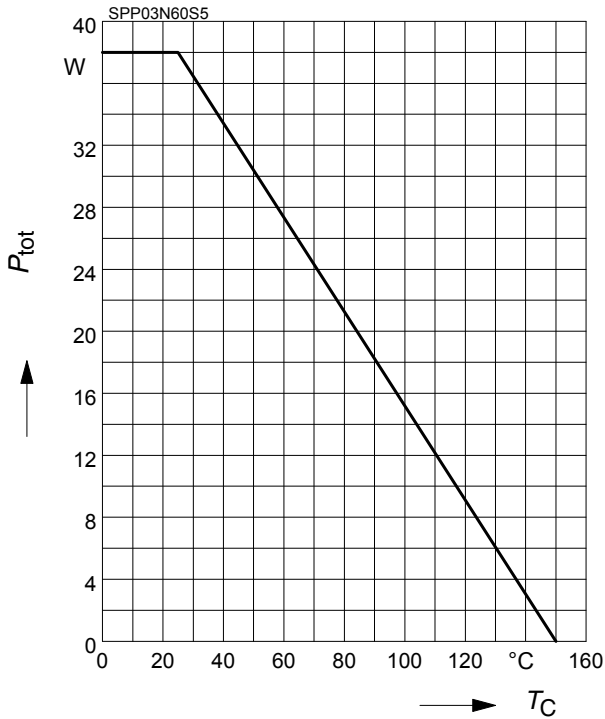
**Typical Transient Thermal Characteristics**

Symbol	Value	Unit	Symbol	Value	Unit
	typ.			typ.	
Thermal resistance			Thermal capacitance		
$R_{th1}$	0.054	K/W	$C_{th1}$	0.00005232	Ws/K
$R_{th2}$	0.103		$C_{th2}$	0.0002034	
$R_{th3}$	0.178		$C_{th3}$	0.0002963	
$R_{th4}$	0.757		$C_{th4}$	0.0009103	
$R_{th5}$	0.682		$C_{th5}$	0.002084	
$R_{th6}$	0.202		$C_{th6}$	0.024	



### 1 Power dissipation

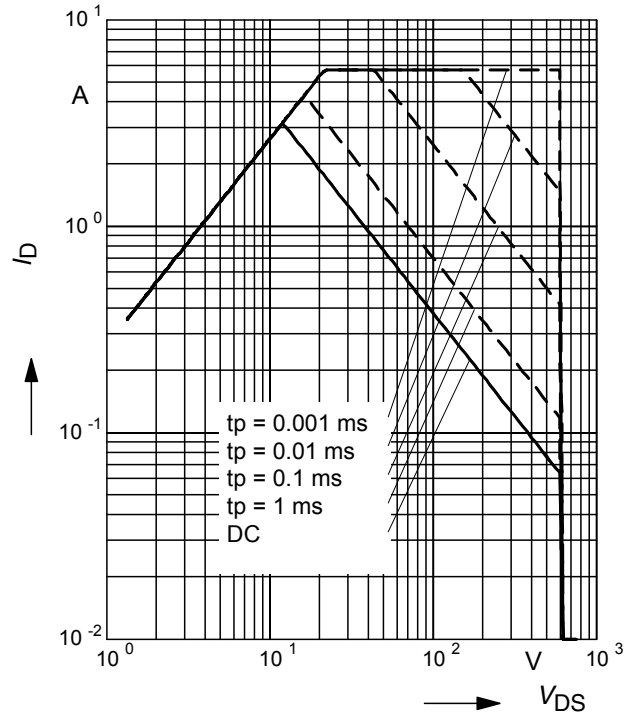
$$P_{tot} = f(T_C)$$



### 2 Safe operating area

$$I_D = f(V_{DS})$$

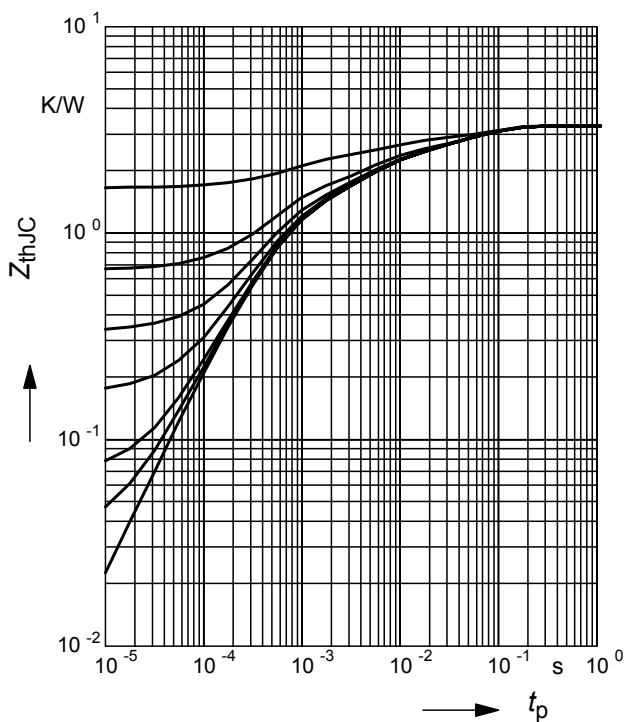
parameter :  $D = 0$  ,  $T_C = 25^\circ\text{C}$



### 3 Transient thermal impedance

$$Z_{thJC} = f(t_p)$$

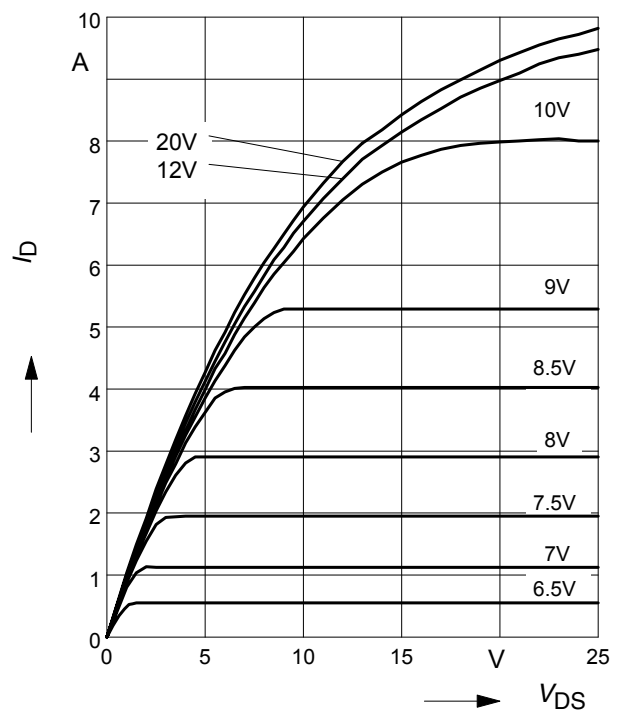
parameter:  $D = t_p/T$



### 4 Typ. output characteristic

$$I_D = f(V_{DS}); T_j = 25^\circ\text{C}$$

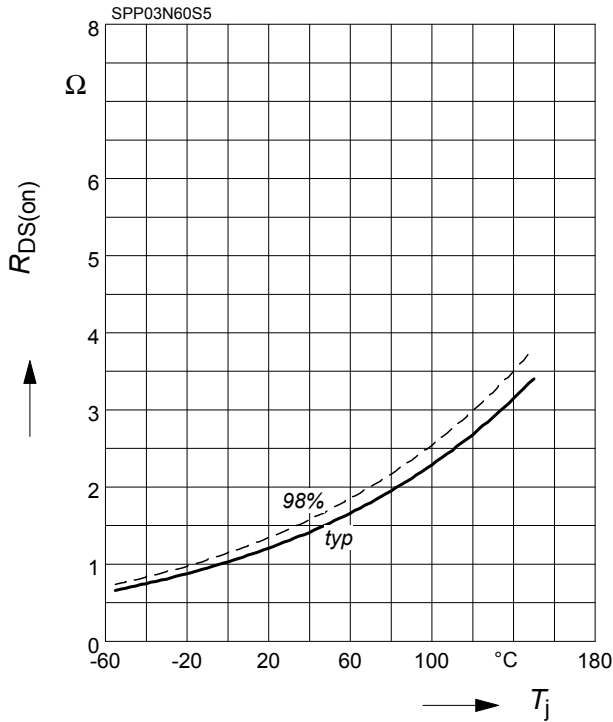
parameter:  $t_p = 10 \mu\text{s}$  ,  $V_{GS}$



**5 Drain-source on-state resistance**

$$R_{DS(on)} = f(T_j)$$

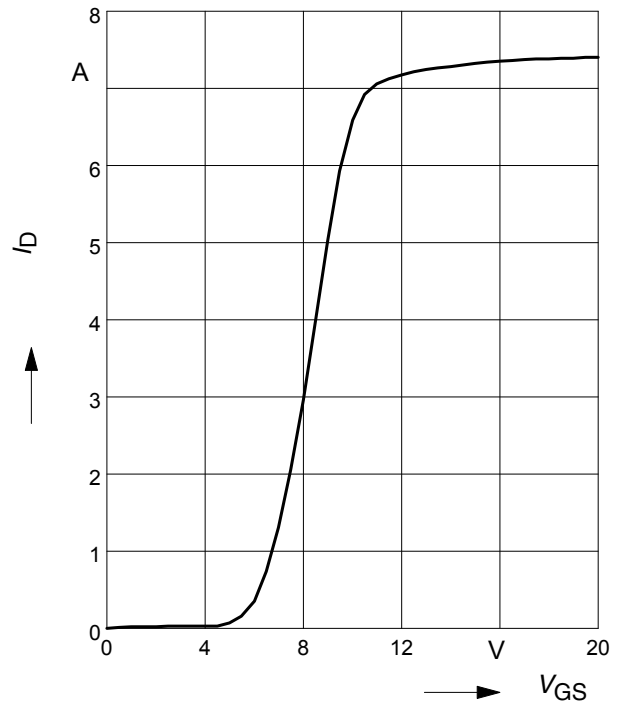
parameter:  $I_D = 2 \text{ A}$ ,  $V_{GS} = 10 \text{ V}$



**6 Typ. transfer characteristics**

$$I_D = f(V_{GS}); V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$$

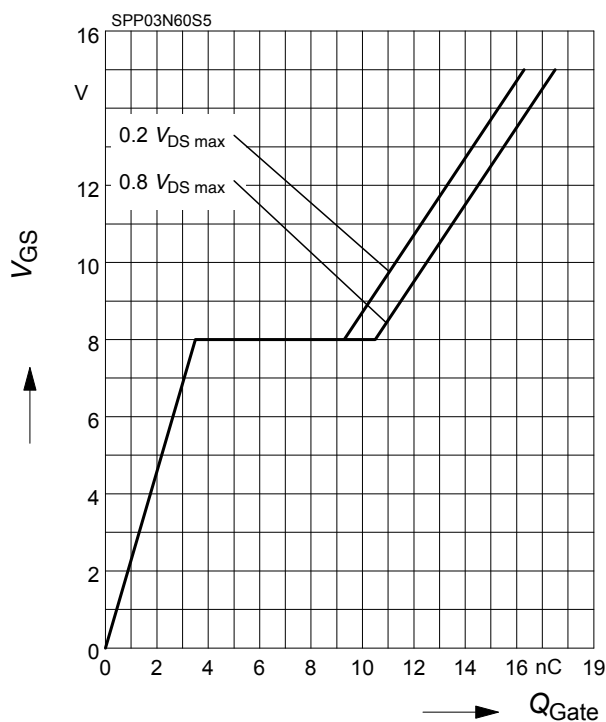
parameter:  $t_p = 10 \mu\text{s}$



**7 Typ. gate charge**

$$V_{GS} = f(Q_{Gate})$$

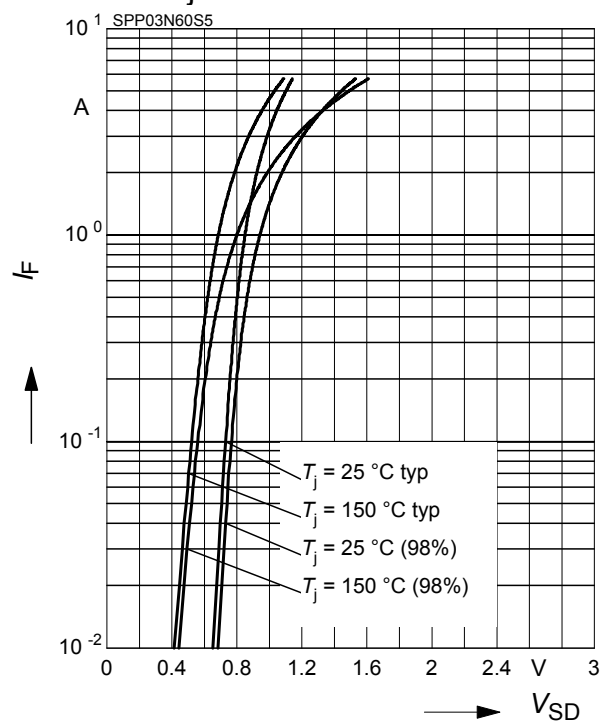
parameter:  $I_D = 3.2 \text{ A pulsed}$



**8 Forward characteristics of body diode**

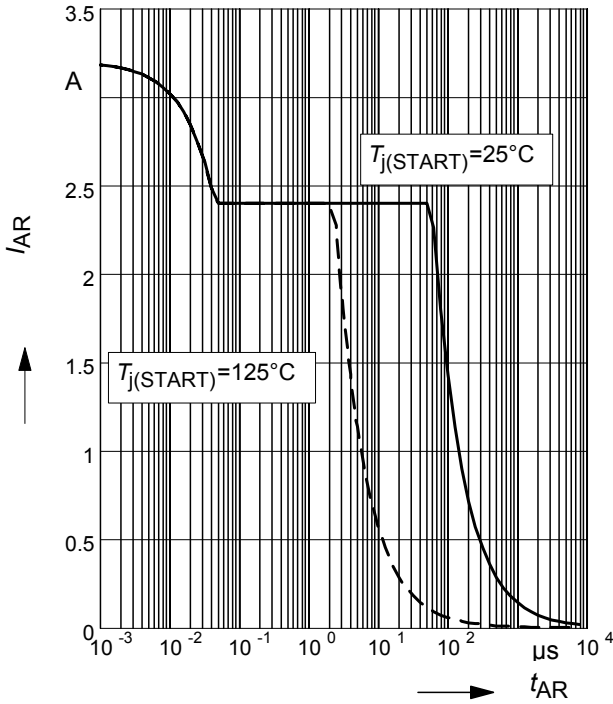
$$I_F = f(V_{SD})$$

parameter:  $T_j$ ,  $t_p = 10 \mu\text{s}$



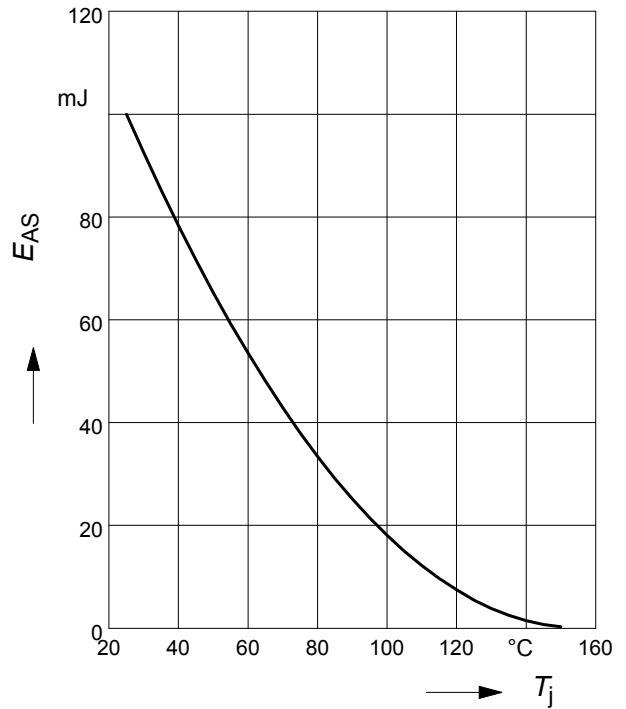
**9 Avalanche SOA**

$I_{AR} = f(t_{AR})$   
 par.:  $T_j \leq 150\text{ }^\circ\text{C}$



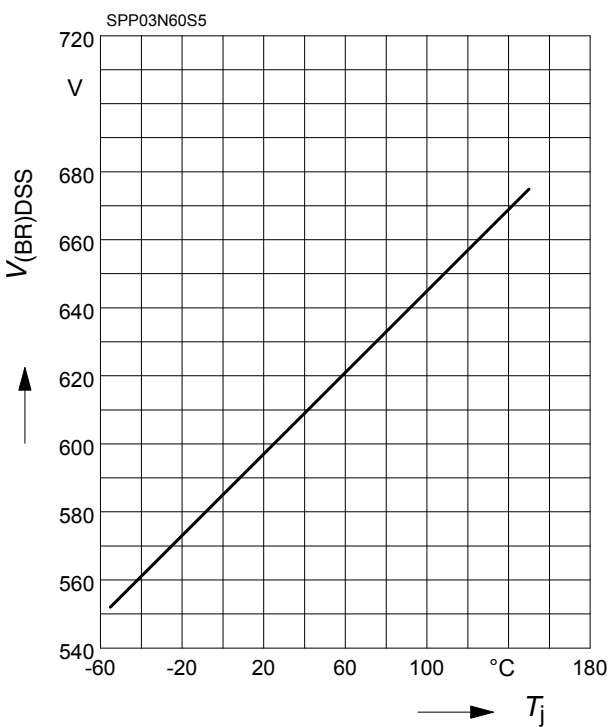
**10 Avalanche energy**

$E_{AS} = f(T_j)$   
 par.:  $I_D = 2.4\text{ A}$ ,  $V_{DD} = 50\text{ V}$



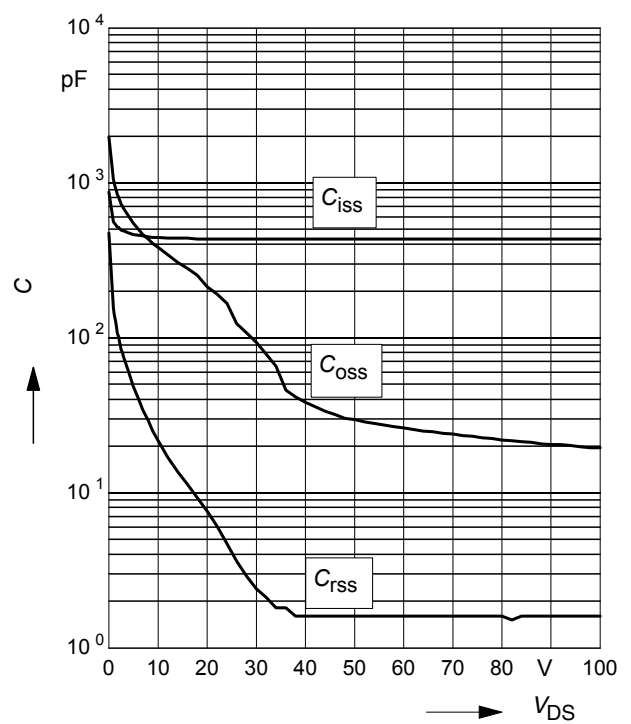
**11 Drain-source breakdown voltage**

$V_{(BR)DSS} = f(T_j)$



**12 Typ. capacitances**

$C = f(V_{DS})$   
 parameter:  $V_{GS} = 0\text{ V}$ ,  $f = 1\text{ MHz}$

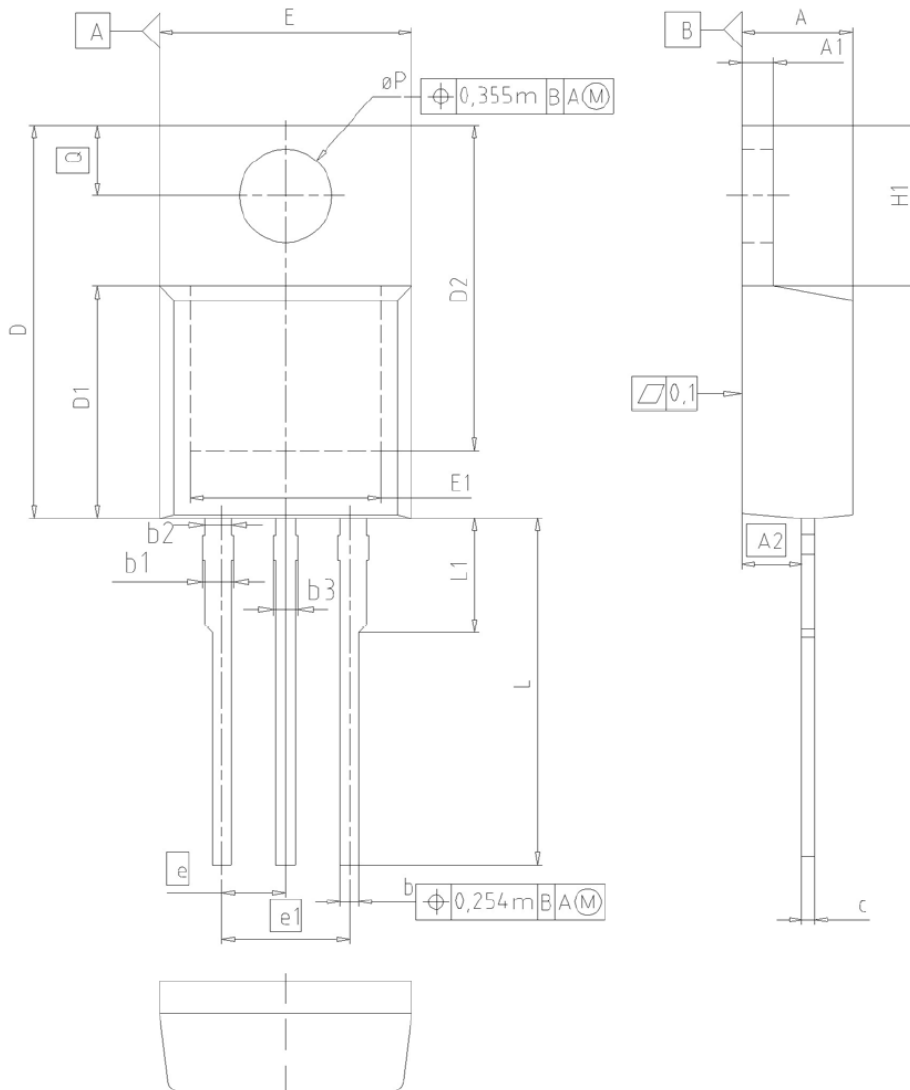


Definition of diodes switching characteristics





PG-TO220-3-1, PG-TO220-3-21



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.30	4.57	0.169	0.180
A1	1.17	1.40	0.046	0.055
A2	2.15	2.72	0.085	0.107
b	0.65	0.86	0.026	0.034
b1	0.95	1.40	0.037	0.055
b2	0.95	1.15	0.037	0.045
b3	0.65	1.15	0.026	0.045
c	0.33	0.60	0.013	0.024
D	14.81	15.95	0.583	0.628
D1	8.51	9.45	0.335	0.372
D2	12.19	13.10	0.480	0.516
E	9.70	10.36	0.382	0.408
E1	6.50	8.60	0.256	0.339
e	2.54		0.100	
e1	5.08		0.200	
N	3		3	
H1	5.90	6.90	0.232	0.272
L	13.00	14.00	0.512	0.551
L1	-	4.80	-	0.189
$\phi P$	3.60	3.89	0.142	0.153
Q	2.60	3.00	0.102	0.118

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